



Patent

Customer No. 31561
Attorney Docket No. 9223-US-PA
Application No.: 10/064,644

I Fw

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Instant application of

Applicant : Hsu
Application No. : 10/064,644
Filed : 2002/08/02
For : FLIP-CHIP DIE FOR JOINING WITH A FLIP-CHIP
SUBSTRATE
Patent No. : 6,710,459 B2
Issue date : 2004/3/23

REQUEST FOR OBTAINING PATENT GRANT

VIA COURIER
(Total pages: 2)

U.S. Patent and Trademark Office
Commissioner for Patents
220 20th Street South
Customer Window
Crystal Plaza Two, Lobby, Room 1B03
Arlington, Virginia 22202

Dear Sir:

It is indicated in the Patent Application Information Retrieval (PAIR) that the patent grant for the above-identified patent has been mailed to Applicant on the date of April 1, 2004. A printout of the message shown in the PAIR is attached herewith for reference. However, so far the same has not yet been received.

Applicant hereby requests your authority to verify the postal status of the said patent grant. If the status is such that the said patent grant is lost in the postal service, please re-arrange to forward the same to Applicant at your earliest convenience.

I believe that no fee is incurred by this request as the safe delivery of the said patent grant is entirely not Applicant's responsibility. However, the Commissioner is authorized to charge any fee required in connection with this request to Deposit Account No. 50-2620 (Order No.: 9223-US-PA).

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A prepaid return postcard is enclosed.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact the undersigned.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: Nov. 19, 2004

By: Belinda Lee
Belinda Lee
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: 10/064,644

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